

NCE N-Channel Super Trench Power MOSFET

Description

The NCEP0225G uses Super Trench technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{\text{DS}(\text{ON})}$ and $Q_{\text{g}}.$ This device is ideal for high-frequency switching and synchronous rectification.

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

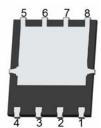
General Features

- V_{DS} =200V,I_D =25A $R_{DS(ON)}$ =33m Ω (typical) @ V_{GS} =10V
- Excellent gate charge x R_{DS(on)} product(FOM)
- Very low on-resistance R_{DS(on)}
- 150 °C operating temperature
- Pb-free lead plating

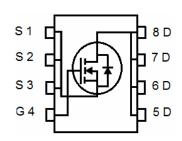
100% UIS TESTED! 100% AVds TESTED!

DFN 5X6





Top View Bottom View



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity	
P0225G	NCEP0225G	DFN5X6-8L	-	-	-	

Absolute Maximum Ratings (T_A=25 °C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	200	V
Gate-Source Voltage	V_{GS}	±20	V
Drain Current-Continuous	I _D	25	Α
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	17.6	А
Pulsed Drain Current ^(Note 1)	I _{DM}	100	А
Maximum Power Dissipation	P _D	135	W
Derating factor		1.08	W/°C
Single pulse avalanche energy (Note 5)	E _{AS}	320	mJ
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Résistance, Junction-to-Case ^(Note 2)	R _{eJC}	0.93	°C/W
Thermal Résistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	50	°C/W



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Electrical Characteristics (T_A =25 $^{\circ}$ C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	200	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =200V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)			•	•		
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	2.5	3.5	4.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =20A	-	33	40	mΩ
Forward Transconductance	g Fs	V _{DS} =5V,I _D =20A	15	-	-	S
Dynamic Characteristics (Note4)			•			
Input Capacitance	C _{lss}	\/ 400\/\/ 0\/	-	1660	2000	PF
Output Capacitance	C _{oss}	V_{DS} =100V, V_{GS} =0V, F=1.0MHz	-	130		PF
Reverse Transfer Capacitance	C _{rss}	r=1.0lvlm2	-	5.4		PF
Switching Characteristics (Note 4)			•	•		
Turn-on Delay Time	t _{d(on)}		-	7	14	nS
Turn-on Rise Time	t _r	V_{DD} =100V, RL=7.5 Ω	-	9	16	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{G} =3 Ω	-	25	42	nS
Turn-Off Fall Time	t _f		-	5	9	nS
Total Gate Charge	Qg	\/ -400\/ -204	-	28	36	nC
Gate-Source Charge	Q _{gs}	V _{DS} =100V,I _D =20A,	-	11	14	nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	5.9	8	nC
Drain-Source Diode Characteristics			•	•		
Diode Forward Voltage (Note 3)	V_{SD}	V_{GS} =0 V , I_{S} =20 A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	25	Α
Reverse Recovery Time	t _{rr}	$T_J = 25^{\circ}C, I_F = I_S$	-	45	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	160	-	nC

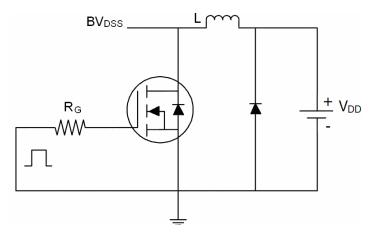
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,V $_{DD}$ =50 V,V $_{G}$ =10 V,L=0.5 mH,Rg=25 Ω

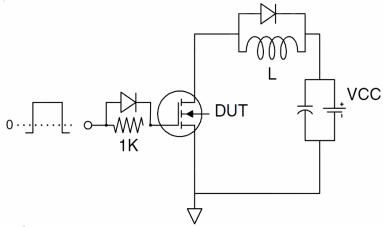


Test Circuit

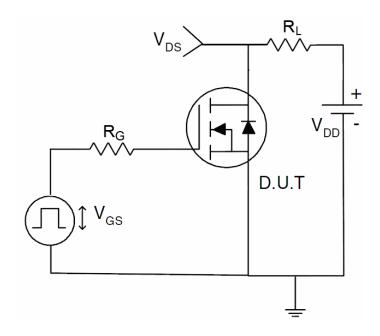
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit





Typical Electrical and Thermal Characteristics

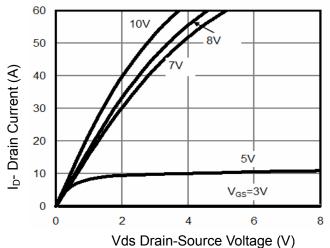


Figure 1 Output Characteristics

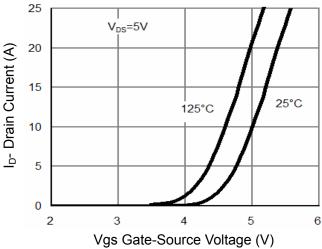


Figure 2 Transfer Characteristics

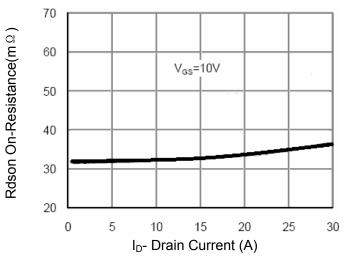


Figure 3 Rdson- Drain Current

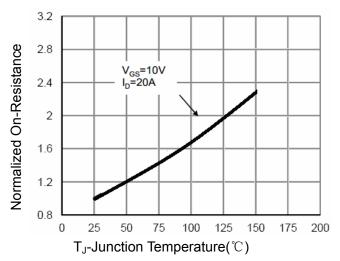


Figure 4 Rdson-Junction Temperature

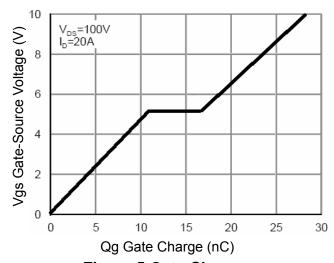


Figure 5 Gate Charge

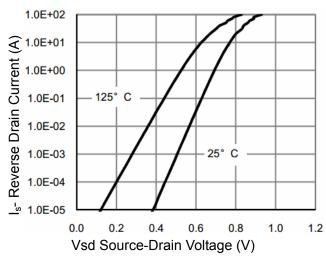


Figure 6 Source- Drain Diode Forward



lp- Drain Current (A)

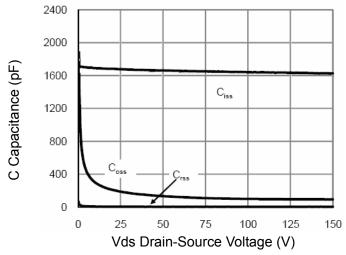


Figure 7 Capacitance vs Vds

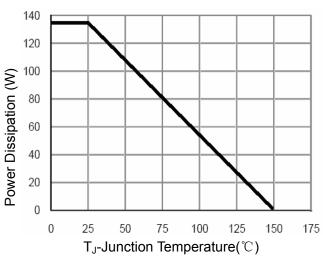


Figure 9 Power De-rating

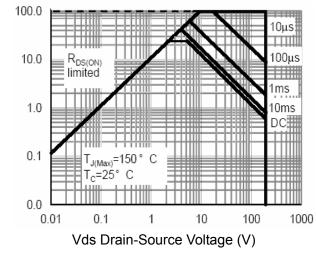


Figure 8 Safe Operation Area

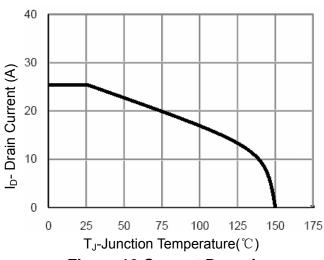
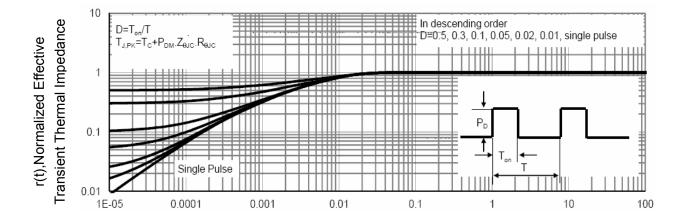


Figure 10 Current De-rating

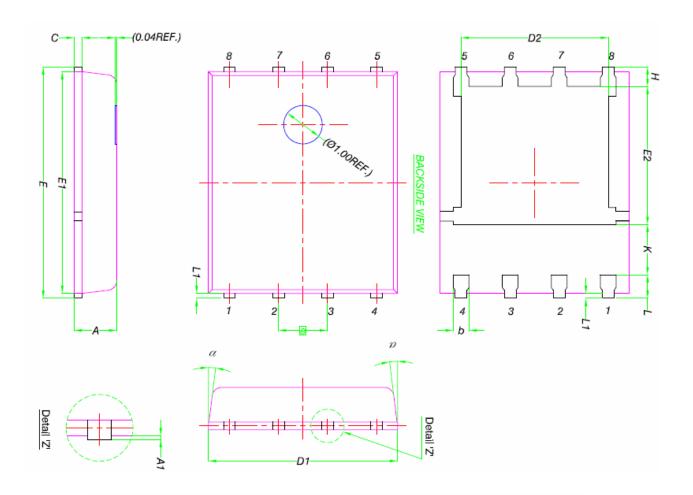


Square Wave Pluse Duration(sec)

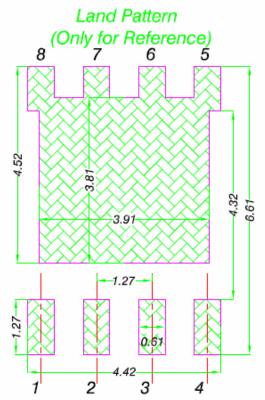
Figure 11 Normalized Maximum Transient Thermal Impedance



DFN5X6-8L Package Information



DIM.	MILLIMETERS				
	MIN.	NOM.	MAX.		
Α	0.90	1.00	1.10		
A1	0	-	0.05		
b	0.33	0.41	0.51		
С	0.20	0.25	0.30		
D1	4.80	4.90	5.00		
D2	3.61	3.81	3.96		
Ε	5.90	6.00	6.10		
E1	5.70	5.75	5.80		
E2	3.38	3.58	3.78		
е	1.27 BSC				
Н	0.41	0.51	0.61		
K	1.10	-	-		
L	0.51	0.61	0.71		
L1	0.06	0.13	0.20		
α	<i>0</i> °	-	12°		





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